AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A substrate processing device, comprising:

a plurality of vacuum process chambers, each of which administers a prescribed process to a substrate therein;

a through-chamber which constitutes a vacuum chamber, the plurality of vacuum process chambers are hermetically-connected to a perimeter of the through-chamber;

a carry system which carries a substrate in sequence, via the through-chamber, to the plurality of vacuum process chambers, the carry system comprises a substrate holder which holds the substrate upright in such a way that a plate surface thereof forms an angle to the horizontal of between 45° and 90°; ~~and~~

a horizontal movement mechanism which moves the substrate holder via the through-chamber to the plurality of vacuum process chambers; and

an alignment chamber hermetically connected to the through chamber;

wherein when the substrate holder is in the alignment chamber, the horizontal movement mechanism is able to move the substrate holder such that a substrate being held in the substrate holder is able to move sideways with respect to a longitudinal direction of the plate surface thereof, as well as in the longitudinal direction thereof so as to align the carry system with the through-chamber.

2. (Original) The substrate processing device described in Claim 1, wherein the through-chamber constitutes a direction-altering chamber comprising a direction-altering mechanism which alters the direction of movement of the substrate holder using the horizontal movement mechanism, wherein the direction-altering mechanism alters the direction of movement by rotating the substrate holder and the horizontal movement mechanism about a vertical rotating axis.

3. (Original) The substrate processing device described in Claim 2, wherein the direction-altering mechanism rotates the substrate holder and the horizontal movement mechanism about a rotating axis coincident with a center axis of the direction-altering chamber.

4. (Original) The substrate processing device described in Claim 1, wherein the substrate holder holds two substrates simultaneously.

5. (Original) The substrate processing device described in Claim 4, wherein the substrate holder holds the substrates upright in such a way that the plate surface thereof forms an angle to the horizontal of between 60° and 90°.

6. (Currently Amended) A substrate processing device, comprising:

a plurality of through-chambers, each of which includes a hermetically-connected vacuum chamber;

a plurality of processing chambers that are hermetically-connected to the plurality of through-chambers;

a carry system that carries a substrate in sequence to the processing chambers, the carry system comprises a substrate holder which holds the substrate upright in such a way that a plate surface thereof forms an angle to the horizontal of between 45° and 90°; ~~and~~

a horizontal movement mechanism which moves the substrate holder to each of the processing chambers via at least a plurality of the through-chambers; and

an alignment chamber hermetically connected to one of the through chambers;

wherein when the substrate holder is in the alignment chamber, the horizontal movement mechanism is able to move the substrate holder such that a substrate being held in the substrate holder is able to move sideways with respect to a longitudinal direction of the plate surface thereof, as well as in the longitudinal direction thereof so as to align the carry system with the one through-chamber.

7. (Original) The substrate processing device described in Claim 6, wherein the through-chambers each constitutes a direction-altering chamber comprising a direction-altering mechanism which alters the direction of movement of the substrate holder using the horizontal movement mechanism, wherein the direction-altering mechanism alters the direction of movement by rotating the substrate holder and the horizontal movement mechanism about a vertical rotating axis.

8. (Original) The substrate processing device described in Claim 7, wherein the direction-altering mechanism rotates the substrate holder and the horizontal movement mechanism about a rotating axis coincident with a center axis of the direction-altering chamber.

9, (Original) The substrate processing device described in Claim 6, wherein the substrate holder holds two substrates simultaneously.

10. (Original) The substrate processing device described in Claim 9, wherein the substrate holder holds the substrates upright in such a way that the plate surface thereof forms an angle to the horizontal of between 60° and 90°.

11. (Currently Amended) A through-chamber having a perimeter to which a plurality of vacuum processing chambers are hermetically-connected, the through chamber comprising:

a vacuum chamber;

a horizontal movement mechanism including a substrate holder for holding a substrate, the horizontal movement mechanism horizontally moves the substrate holder through the vacuum chamber, and the substrate holder holds the abovementioned substrate upright in such a way that the plate surface thereof forms a holding angle to the horizontal of between 45° and 90°, ~~and~~

a direction-altering mechanism which alters the direction of movement of the substrate holder by rotating the substrate holder and horizontal movement mechanism about a vertical rotating axis; and

an alignment chamber hermetically connected to the through chamber;

wherein when the substrate holder is in the alignment chamber, the horizontal movement mechanism is able to move the substrate holder such that a substrate being held in the substrate holder is able to move sideways with respect to a longitudinal direction of the plate surface thereof, as well as in the longitudinal direction thereof so as to align the carry system with the through-chamber.

12. (Original) The through-chamber as described in Claim 11, wherein the direction-altering mechanism rotates the substrate holder and the horizontal movement mechanism about a rotating axis coincident with a center axis of the through-chamber.

13. (New) The substrate processing device described in Claim 1, further comprising a heater in the alignment chamber.

14. (New) The substrate processing device described in Claim 6, further comprising a heater in the alignment chamber.

15. (New) The substrate processing device described in Claim 11, further comprising a heater in the alignment chamber.